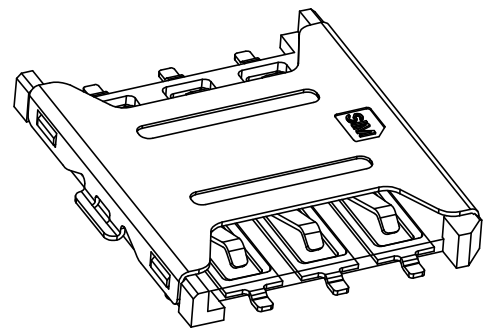
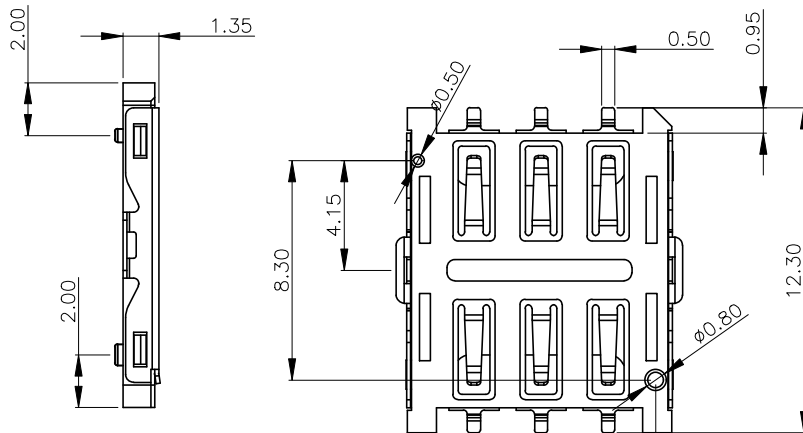
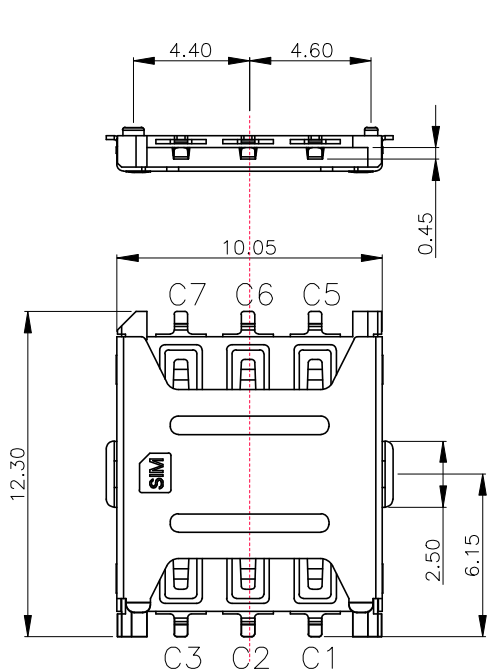
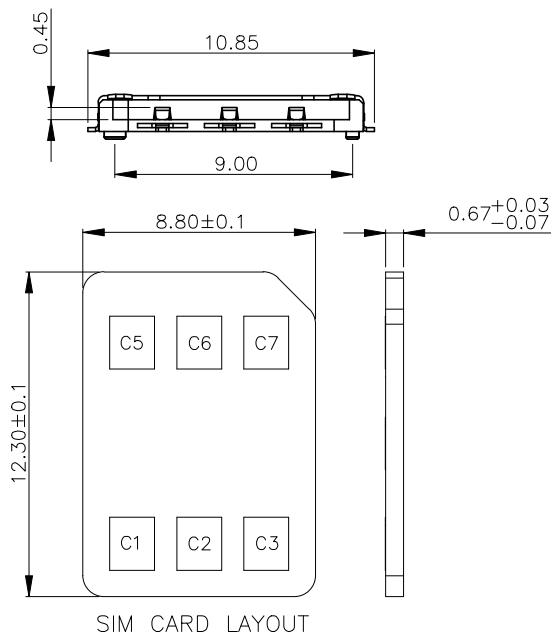
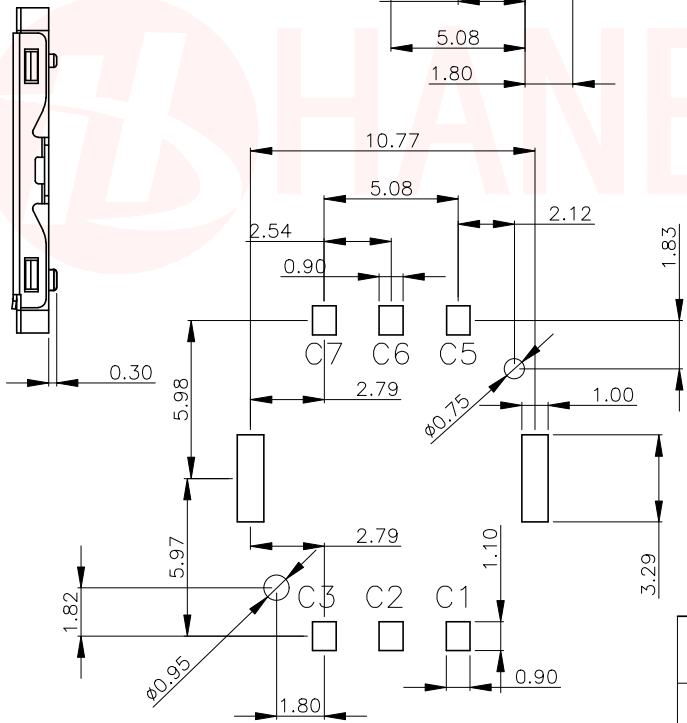




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



**SPECIFICATION**  
**MATERIAL:**  
 INSULATOR: HIGH TEMPERATURE THERMOPLASTIC,UL 94V-0.  
 CONTACT: C5210  
 SHELL: SUS  
**PLATING:**  
 CONTACT: PLATED 50U" NI OVERALL CONTACT ALL AU 1U  
 SHELL: PLATED 50U" NI OVERALL,PAD AU 1U  
**ELECTRICAL:**  
 CURRENT RATING: 0.5MA AC/DC MAX  
 VOLTAGE RATING: 125V AC/DC  
 AMBIENT TEMPERATURE RANGE: -20°C~+60°C  
 STORAGE TEMPERATURE RANGE: -40°C~+70°C  
 AMBIENT HUMIDITY RANGE: 95% R.H. MAX.  
 CONTACT RESISTANCE: 100MΩMAX.  
 INSULATION RESISTANCE: 1000MΩMIN./500VDC  
 REFLOW PEAK TEMP: 260°C ±5°C, 3~5 S  
 MATING CYCLES: 5,000 INSERTIONS MIN



**RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE:±0.05)**  
**RECOMMENDED MATAL MASK T=0.12MM**

UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD			
DECIMALS:	ANGLES:	TITLE	6Pin 1.35H PUSH PULL Nano SIM CARD CONN.		
X :±0.30	X :±2°	DWN	xiong	PART NO. SNO-1390	
X.X :±0.20	X.X :±1°	CHKD	lee	SCALE:1:1	UNIT: mm
X.XX :±0.10		APVD	wang	SIZE: A4	SHEET:10F 1
		REV: A4			
CUSTOMER COPY					